EAST Search History

L41	0	(circuit adj1 (board or substrate)) and (mounting adj1 pads) and ((broad or wide) adj1 (pad)) and (thin adj1 (film or layer)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:33
L42	134	(circuit adj1 (board or substrate)) and ((conductive or circuit) adj1 (lines or traces)) and (mounting adj1 pads) .clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:33
L43	0	(circuit adj1 (board or substrate)) and ((conductive or circuit) adj1 (lines or traces)) and (mounting adj1 pads) and (smart adj1 card) . clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:34
L44	5	(circuit adj1 (board or substrate)) and (mounting adj1 pads) and (smart adj1 card) .clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:35
L45	15	((conductive or circuit) adj1 (lines or traces)) and (mounting adj1 pads) and (thin adj1 (film or layer)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:35
L46	111	(yasukazu adj2 nakata).in. or (matsuura adj2 katsuyoshi).in. or (matsushita adj2 taiga).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/24 16:37
L47	639	257/679.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:39
L48	638	235/488.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:39

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	37	("5337063" | "5852289" | "5965867" | "6049463" | "6095423" | "6142381" | "6173898" | "6208019").PN. OR ("6412702"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/24 14:36
L5	54	("3956751" | "4021705" | "4864280" | "4922261" | "4947180" | "5108822" | "5128686").PN. OR ("5337063").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/24 14:42
L6	14	("4725924" | "5495250" | "5888624" | "5969951" | "6161761" | "6173898").PN. OR ("6406935"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/24 14:46
L28	2154	361/760.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28
L29	955	361/736.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28
L30	884	361/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28
L31	1242	361/748.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28
L32	229	361/750.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28

L33	288	361/751.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:28
L34	194	361/771.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:29
L35	977	361/767.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:29
L36	1413	174/250.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:29
L37	2093	174/255.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:29
L38	904	174/257.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:30
L39	2680	174/260.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:30
L40	0	(circuit adj1 (board or substrate)) and ((conductive or circuit) adj1 (lines or traces)) and (mounting adj1 pads) and ((broad or wide) adj1 (pad)) and (thin adj1 (film or layer)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/24 16:31